

depositing an organic layer on the inorganic conductive or semiconductive layer, such that the organic layer is in direct physical contact with the inorganic conductive or semiconductive layer;

deforming the substrate such that there is an average radial or biaxial strain of at least 0.05% relative to the original configuration.

REMARKS

The present invention is directed to methods of fabricating devices using deformable substrates. Claims 31-37 are pending.

Discussion of Office Action

In an office action dated April 19, 2005, the Office rejected claims 31-37.

Amendments to the Claims

Claims 31 and 37 have been amended to recite an inorganic layer in an island configuration. This amendment is supported by the specification, *inter alia*, at paragraph [0034], and by claim 2 as originally filed.

Claim 32 has been amended to correct a typographical error.

35 U.S.C. § 102 Rejection

Claims 31-34 and 37 were rejected under 35 U.S.C. § 102 as being anticipated by U.S. Publication No. 2004/0192082 to Wagner et al. ("Wagner").

It is believed that the claims as currently amended are not disclosed in the presently-cited art. Accordingly, Applicants respectfully request that the anticipation rejection be withdrawn.

35 U.S.C. § 103 Rejection

Dependent claims 35-36 were rejected under 35 U.S.C. § 103(a) as being obvious in view of Wagner and the Materials Research Society article by Wang et al. ("Wang").

It is believed that the claims as currently amended are not disclosed in the presently-cited art. Accordingly, Applicants respectfully request that the obviousness rejections be withdrawn.

CONCLUSION

In view of the foregoing amendments and remarks, Applicants respectfully submit that the present application is in condition for allowance. Early and favorable action by the Examiner is earnestly solicited. If the Examiner believes that issues may be resolved by a telephone interview, the Examiner is invited to telephone the undersigned at the number below.

Date:

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Respectfully Submitted,



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